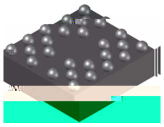
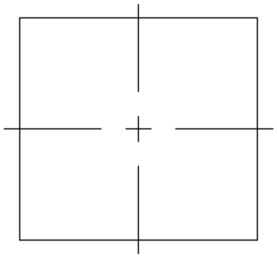
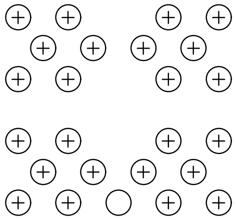
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONSq1 01 458.532 62.123 m 0fQ 01 45q1 01 58.532 62.1592 62.123 m0153o10m.4532 5NE*Q2 62.1592

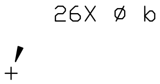


WLCSP26, 2.388x2.233
CASE 567CY
ISSUE B

DATE 29 NOV 2022

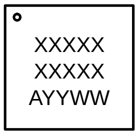






the ON
Semiconductor Soldering and Mounting Techniques
Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb ïFree indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.